

Radiation-Hard Optical Link in the ATLAS Pixel Detector

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May 24, 2004

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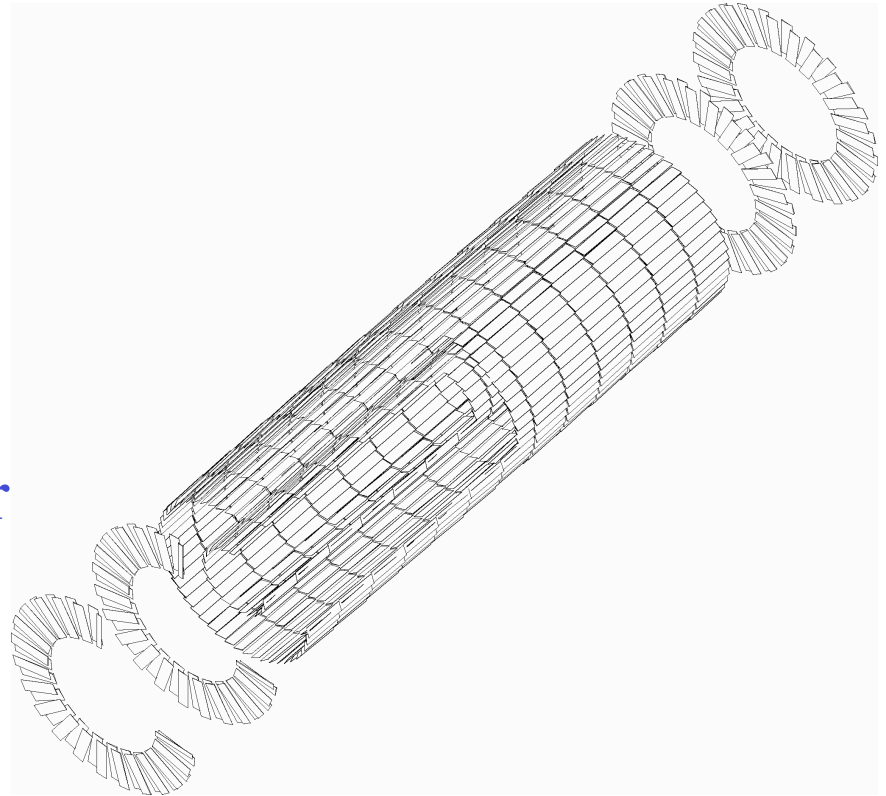
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Universitaet Siegen, Germany

Outline

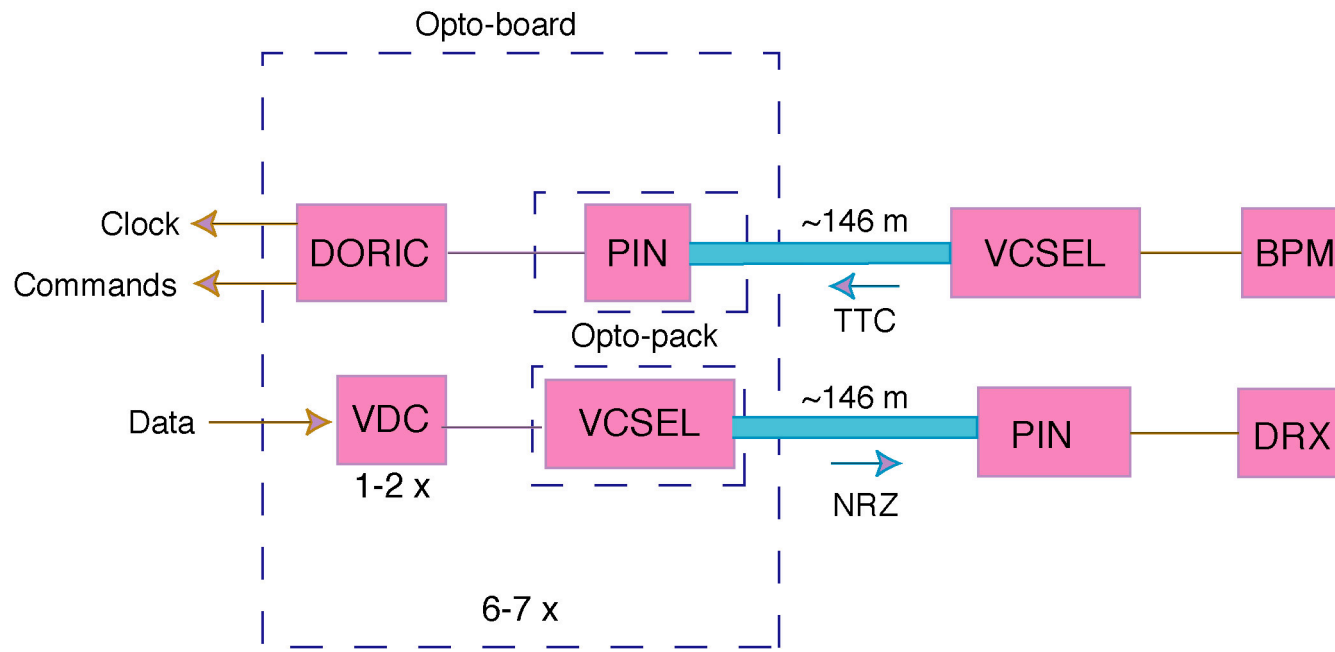
- Introduction
- Results on IBM 0.25 μ m Chips
- Results on Proton Irradiations
- Summary

ATLAS Pixel Detector

- Inner most tracking detector
- Pixel size: $50 \mu\text{m} \times 400 \mu\text{m}$
- 100 million channels
- Barrel layers at $r = 5.1, 12.3 \text{ cm}$
- Disks at $z = 50, 65 \text{ cm}$
- Dosage after 10 years:
 - ◆ optical link: 30 Mrad or $6 \times 10^{14} \text{ 1-MeV } n_{\text{eq}}/\text{cm}^2$



ATLAS Pixel Opto-link



VCSEL: Vertical Cavity Surface Emitting Laser diode

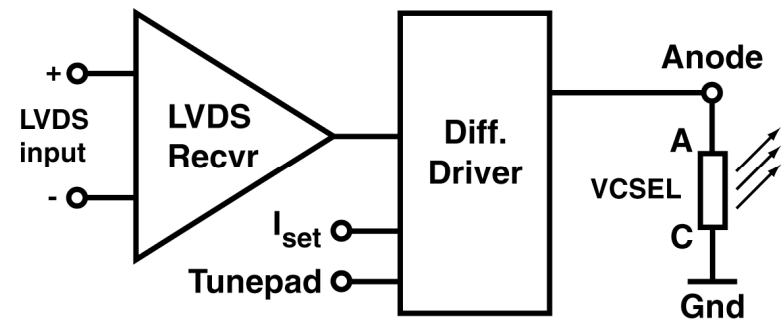
VDC: VCSEL Driver Circuit

PIN: PiN diode

DORIC: Digital Optical Receiver Integrated Circuit

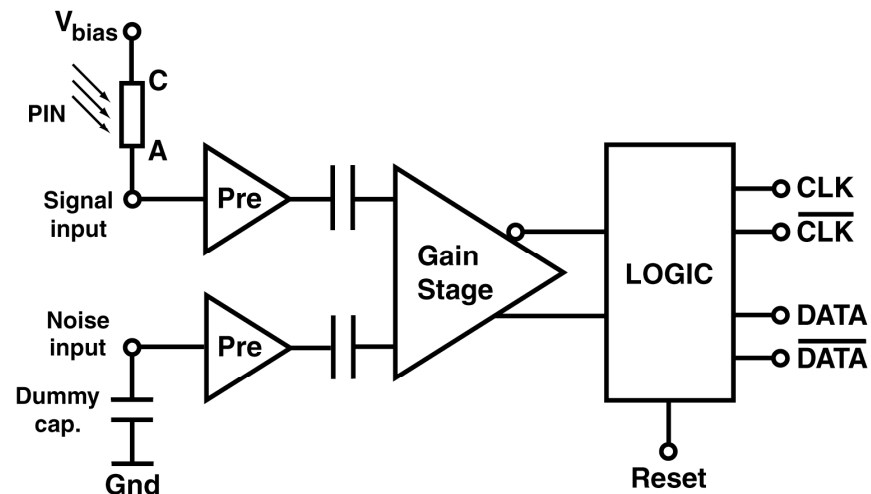
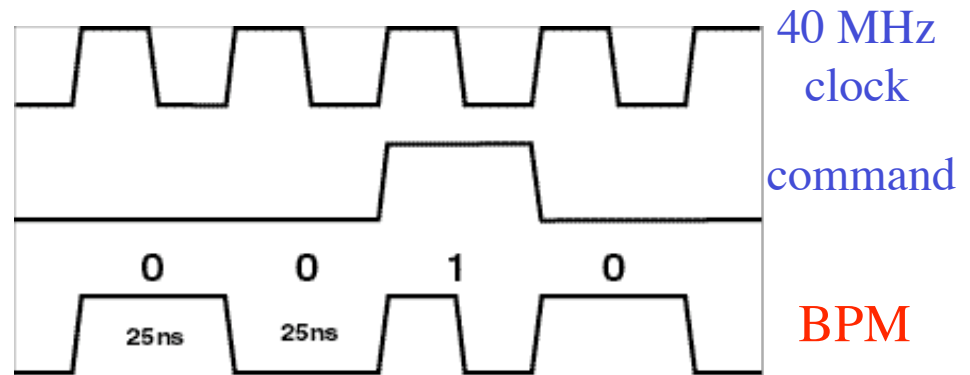
VDC: VCSEL Driver Circuit

- Convert LVDS input signal into single-ended signal appropriate to drive VCSEL diode
- Output (bright) current: 0 to 20 mA
 - ◆ controlled by external current I_{set}
- Standing (dim) current: ~ 1 mA
 - ◆ improve switching speed
- Rise & fall times: 1 ns nominal for 80 MHz signals
- “On” voltage of VCSEL: up to 2.3 V at 20 mA for 2.5 V supply
- Constant current consumption!
- use Truelight high-power oxide common cathode VCSEL array



DORIC: Digital Optical Receiver IC

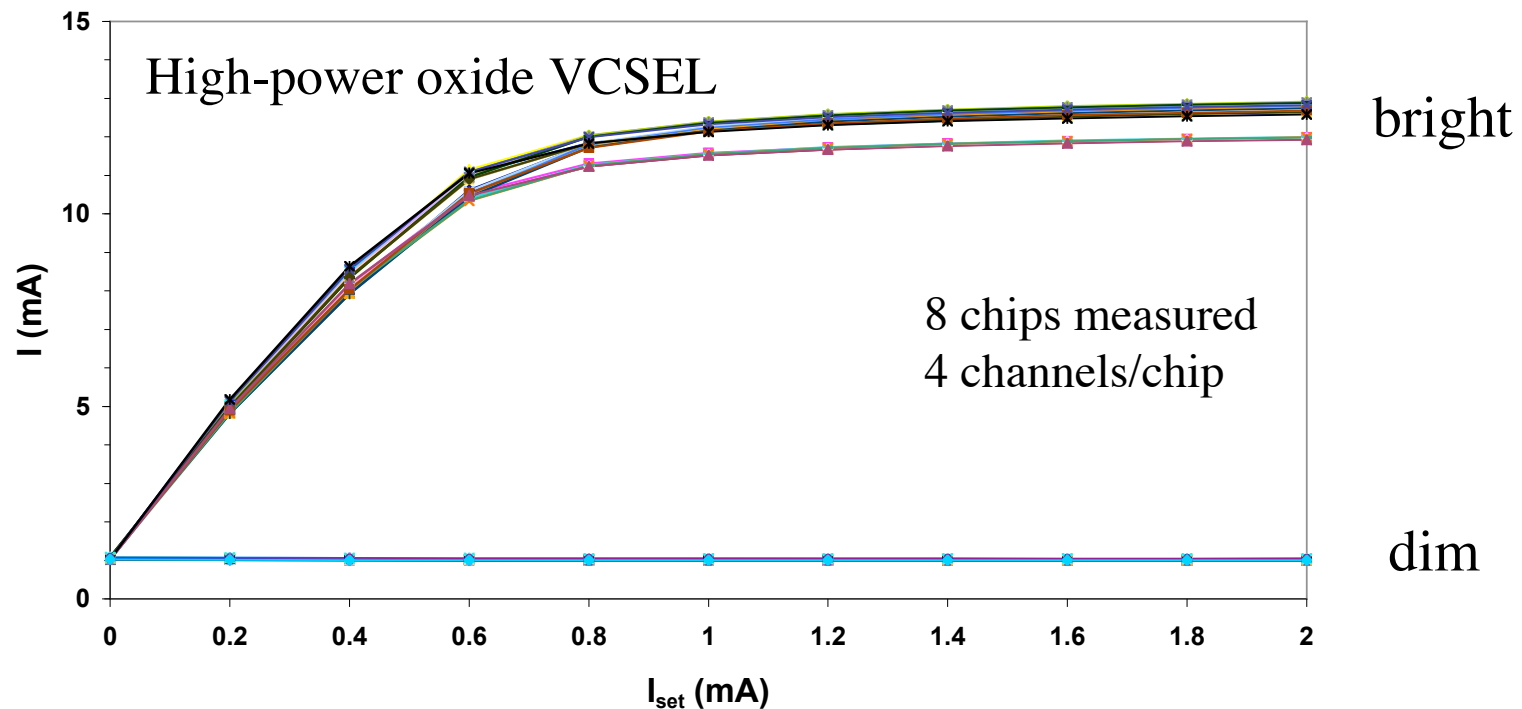
- Decode Bi-Phase Mark encoded (BPM) clock and command signals from PIN diode
- Input signal: 40-600 μA
- Extract: 40 MHz clock
- Duty cycle: $(50 \pm 4)\%$
- Total timing error: $< 1 \text{ ns}$
- Bit Error Rate (BER): $< 10^{-11}$ at end of life
- use Truelight common cathode PIN array



Status of VDC & DORIC

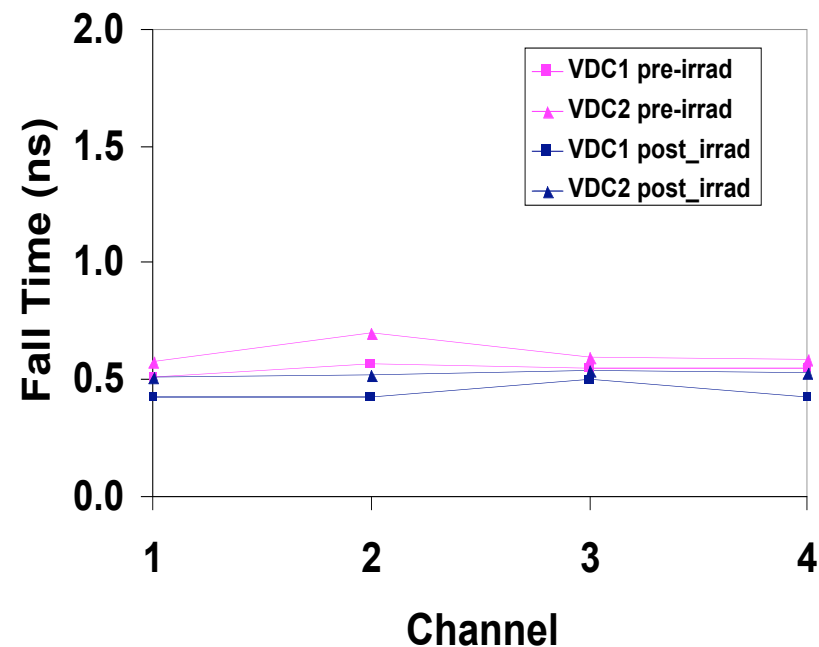
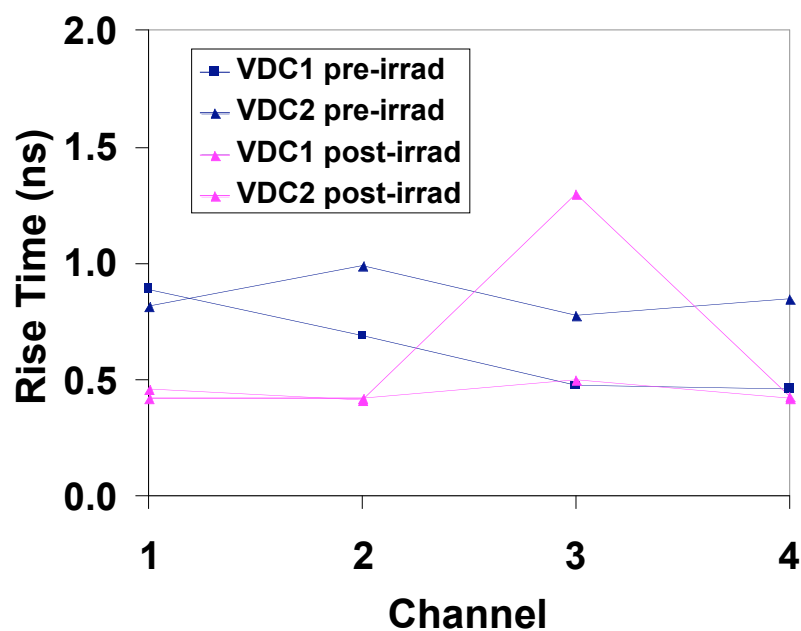
- Original design for ATLAS SemiConductor Tracker (SCT)
 - ❑ AMS 0.8 μ m BiPolar in radiation tolerant process (4 V)
- DMILL #1-3: Summer 1999 - May 2001
 - ❑ 0.8 μ m CMOS rad-hard process (3.2 V)
 - ❑ VDC & DORIC #3: meet specs
 - ❑ severe degradation of circuit performance in April 2001 proton irradiation
- IBM #1-5: Summer 2001 - Dec 2002
 - ❑ 0.25 μ m CMOS rad-hard process (2.5 V)
 - ❑ enclosed layout transistors and guard rings for improved radiation hardness
- IBM 5e: April 2003 engineering run
 - ❑ convert 3-layer to 5-layer layout for submission with pixel Module Control Chip (MCC) for cost saving
 - ⇒ this is the production run since chips meet specs and sufficient quantity of chips were produced

VDC-I5e: Bright and Dim Currents vs. I_{set}



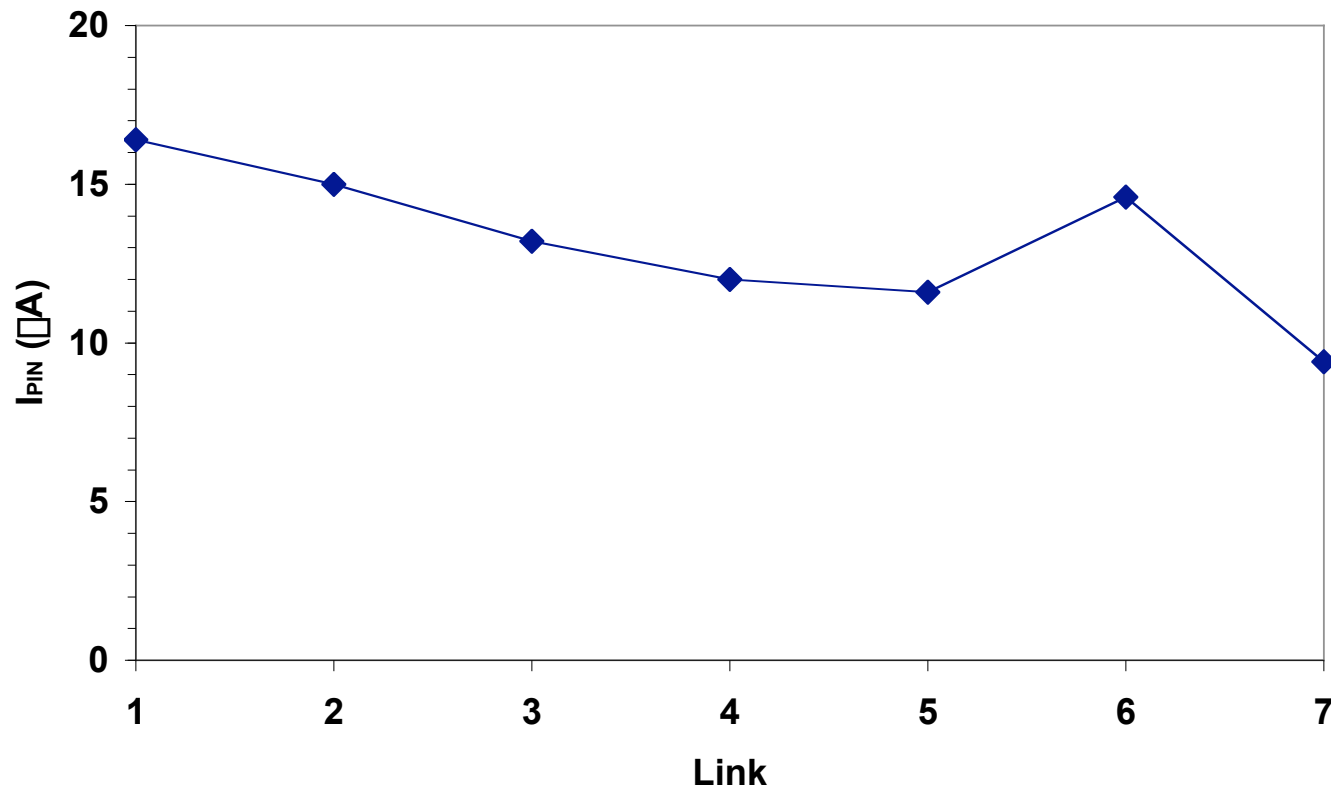
- dim current is ~ 1 mA as expected
- bright current measured with $1 \square$ in series
- maximum bright current is ~ 13 mA
 - ◆ oxide VCSEL has larger effective resistance than p^+ implanted VCSEL
 - ◆ target is 20 mA but 13 mA is adequate for annealing from irradiation damage

VDC-I5e: Clock Rise/Fall Time



- ✓ fall time < 1 ns
- ✗ rise time > 1 ns
 - ◆ measured with 44-pin package
 - ◆ faster rise time on opto-board
- ✓ no degradation up to 62 Mhz

DORIC: PIN Current Thresholds with No Bit Errors

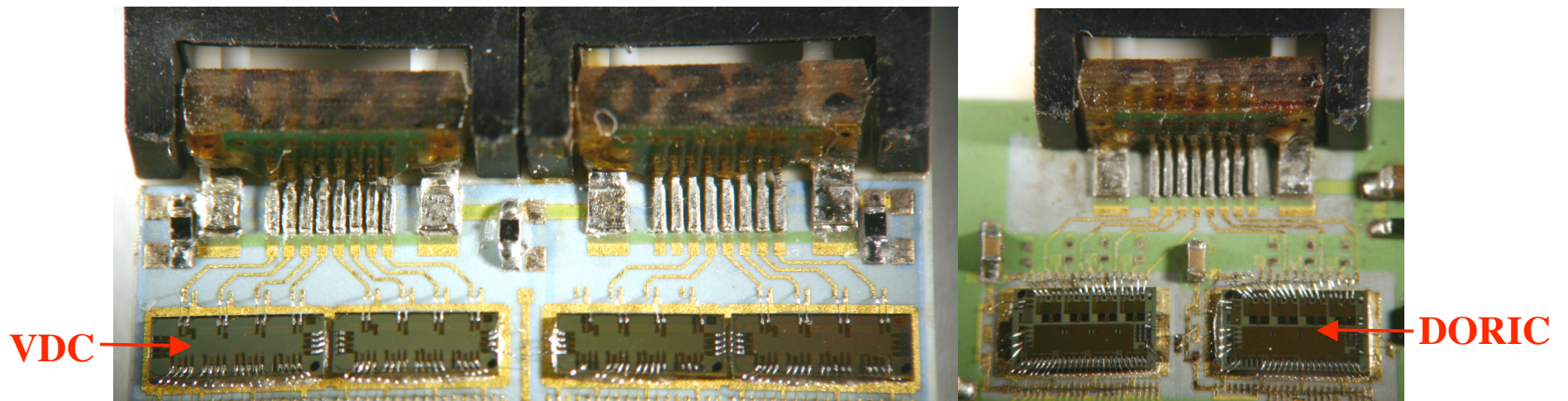
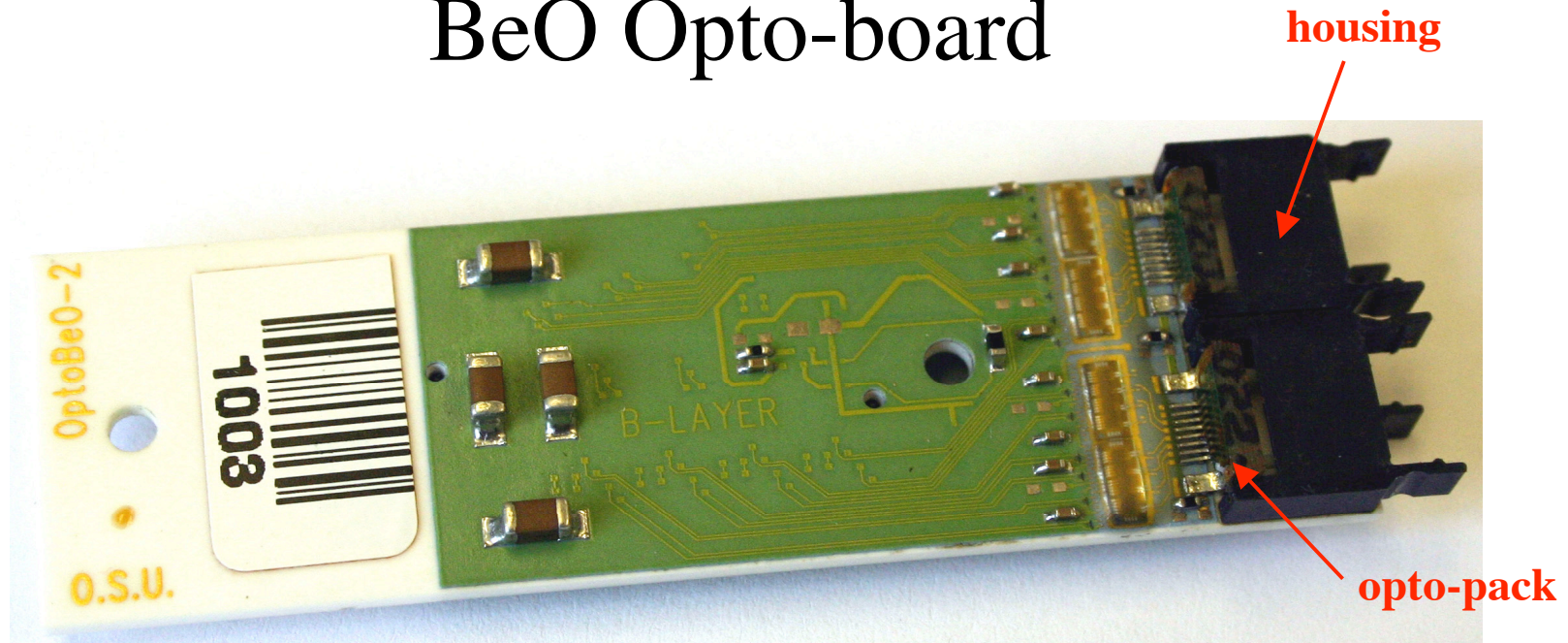


● thresholds significantly better than spec: 40 μA

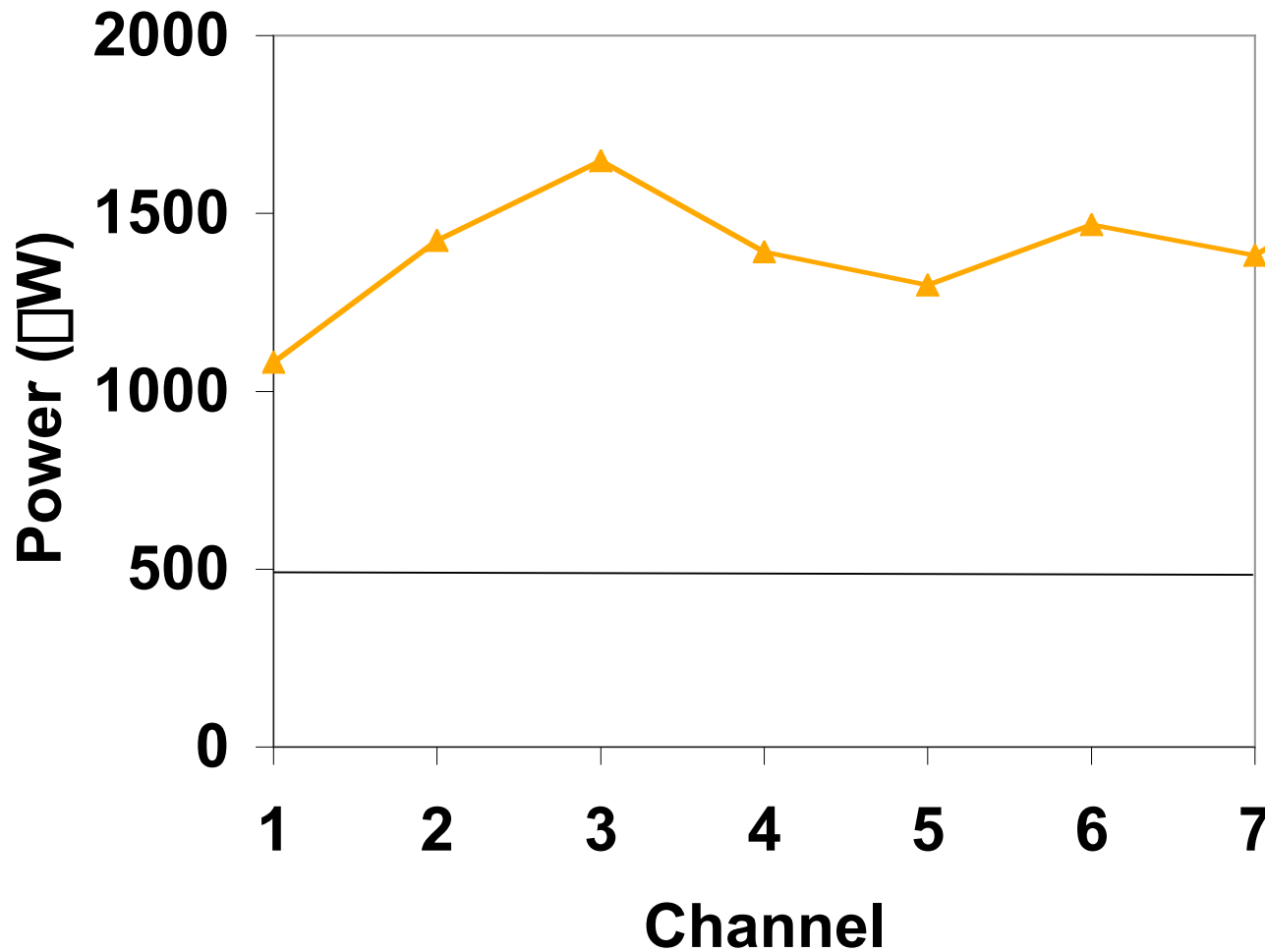
Status of BeO Opto-board

- converts: optical signal ↔ electrical signal
- contains 7 optical links
- use BeO for heat management but prototype initially in FR-4 for fast turnaround and cost saving
- 1st BeO prototype:
 - ◆ many open vias due to insufficient gold filling
 - ✓ opto-links works after via repairs!
- 2nd BeO prototype:
 - ◆ recycled BeO boards
 - ◆ many shorts due to over filling
 - ⇒ use more experienced/expensive vendor
 - ⇒ produced opto-boards of high quality

BeO Opto-board



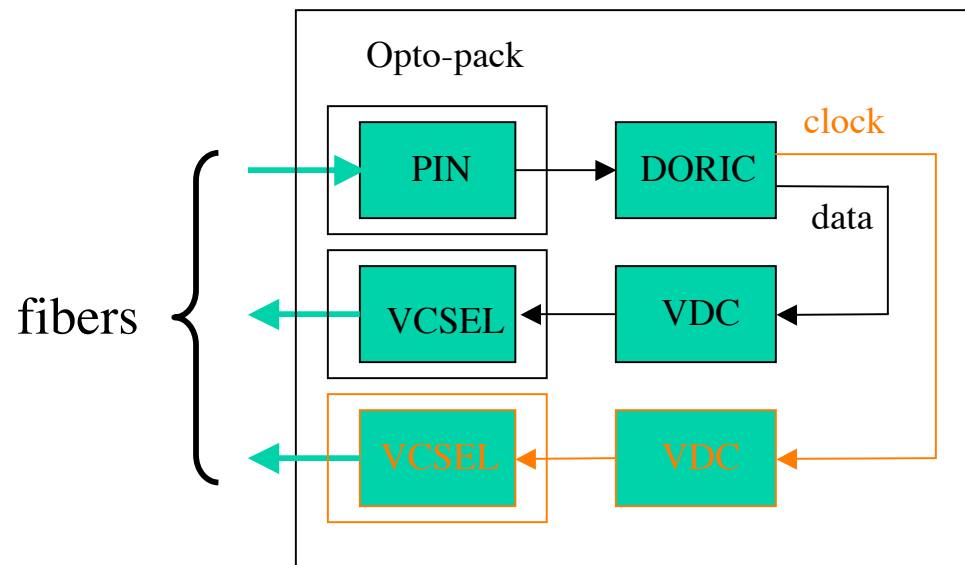
Optical Power



● optical power at 10 mA significantly above spec: 500 mW

Proton Irradiation at CERN

- use 24 GeV protons at T7 to verify radiation hardness of opto-links
- monitor performance of opto-links in real time
- cold box: irradiate 4 VDC-I5e and 4 DORIC-I5e with no optical components
- shuttle: irradiate 4 opto-boards
 - ◆ opto-boards can be moved in and out of beam remotely for VCSEL annealing



Shuttle Test System



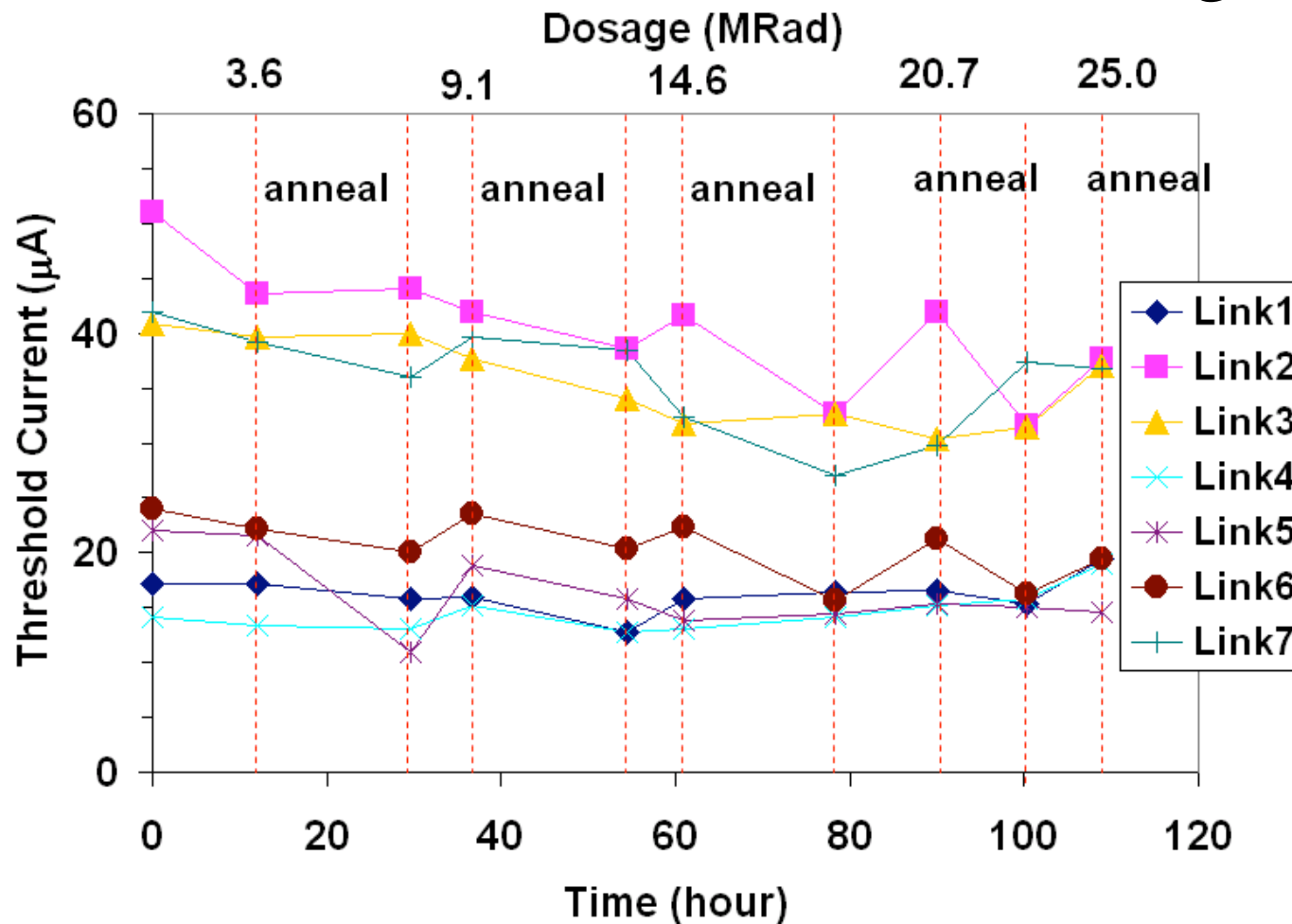
shuttle test electronics
at OSU prior to
shipping to CERN

**opto-board
test system**

20 m fibers/wires spool

opto-boards

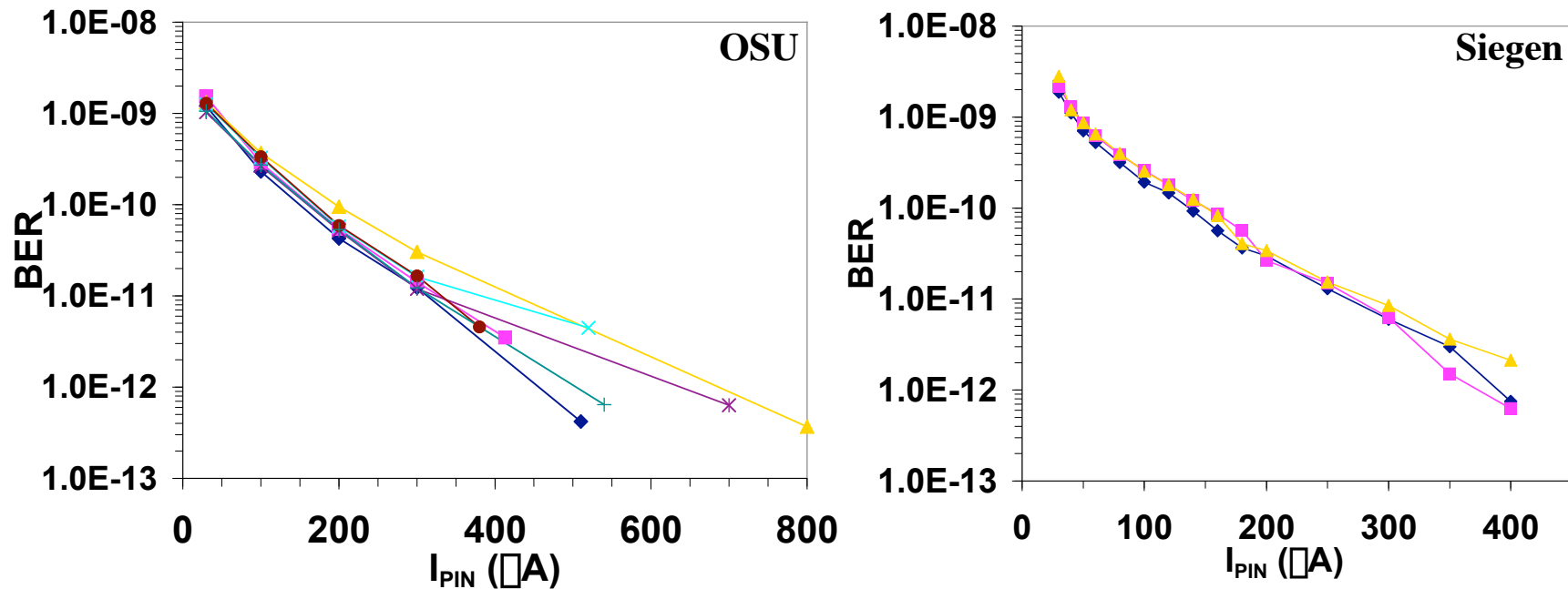
PIN Current Threshold vs Dosage



- PIN current thresholds for no bit errors remain constant

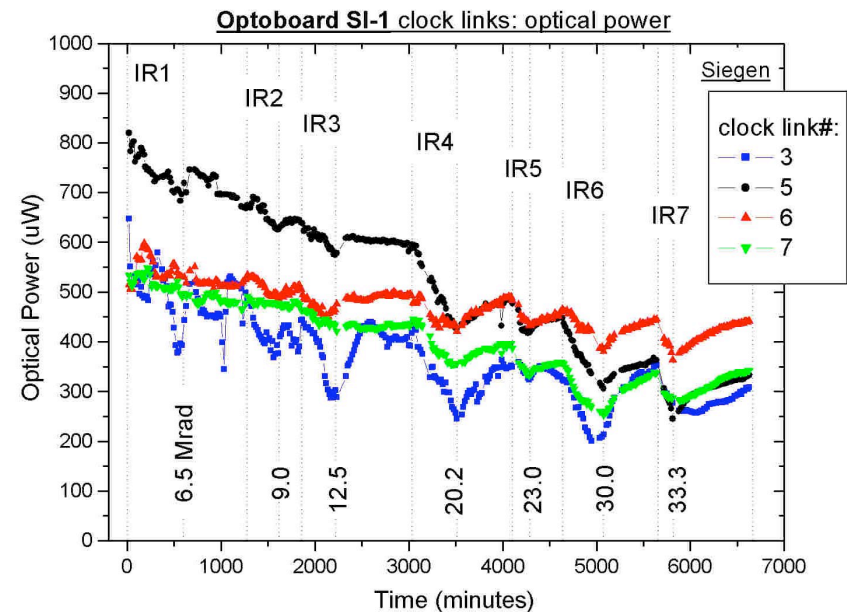
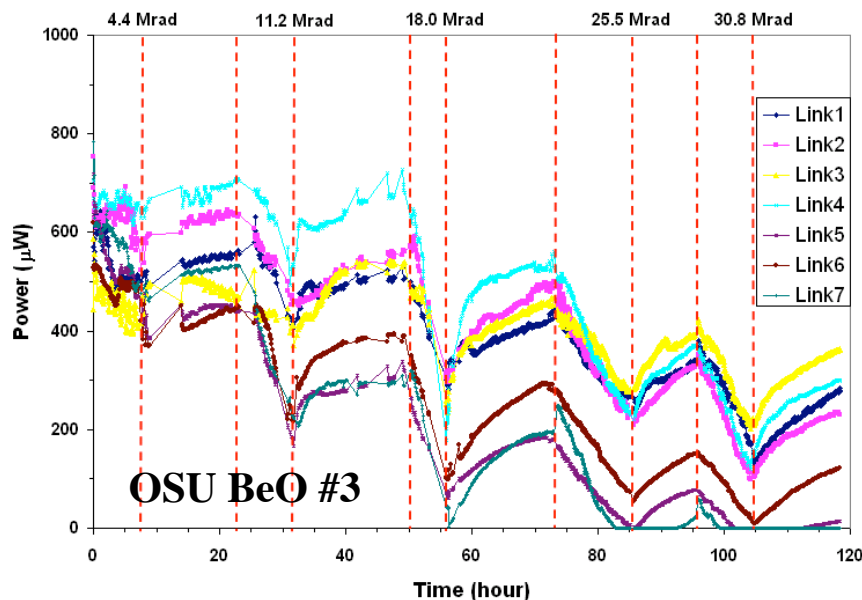
Proton Induced Bit Errors in PIN

- convert observed bit errors into bit error rate at opto-link location:



- bit error rate decreases with increasing PIN current as expected
- bit error rate $\sim 3 \times 10^{-10}$ at 100 μ A (1.4 errors/minute)
- DORIC spec: 10^{-11}

Optical Power vs Dosage



- irradiation procedure: ~ 5 Mrad/day (6 hours) with the rest of day annealing
- optical power decreases with dosage as expected
- annealing at ~ 13 mA recovers some lost power
- optical power satisfies spec after extended annealing at home institutions

Summary

- VDC-I5e & DORIC-I5e (IBM 0.25 μ m):
 - ✓ radiation hard to 62 Mrad
 - ✓ meet ATLAS pixel specs
 - ✓ production is completed
- BeO opto-board:
 - ✓ several pre-production opto-boards have been fabricated
 - low PIN current thresholds for no bit errors
 - excellent optical power
- VCSEL lost significant fraction of optical power after irradiation
 - power satisfies spec after extended annealing at home institutions
- start opto-link production in July 2004